



SPECIFICATION

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N: CL21B102KBANNNC

· Product : Multi-layer Ceramic Capacitor · Description : CAP, 1nF, 50V, ±10%, X7R, 0805

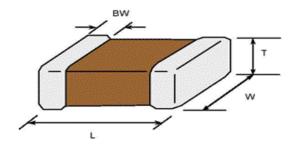
A. Samsung Part Number

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1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0805 (inch code)	L: 2.00	± 0.10 mm	W:	$1.25 \pm 0.10 \; \text{mm}$	
3	Dielectric	X7R	8	Inner electrode		Ni	
4	Capacitance	1 nF		Termination		Cu	
⑤	Capacitance	±10 %		Plating		Sn 100%	(Pb Free)
	tolerance		9	Product		Normal	
6	Rated Voltage	50 V	10	Special		Reserved for fu	uture use
7	Thickness	$0.65 \pm 0.10 \text{ mm}$	11)	Packaging		Cardboard Typ	e, 7" reel

B. Structure & Dimension



Samauna D/N	Dimension(mm)					
Samsung P/N	L	W	Т	BW		
CL21B102KBANNNC	2.00 ± 0.10	1.25 ± 0.10	0.65 ± 0.10	0.50 +0.2/-0.3		

C. Samsung Reliablility Test and Judgement Condition

	Judgement	Test condition		
Capacitance	Within specified tolerance	1kHz ±10% / 1.0±0.2Vrms		
Tan δ (DF)	0.025 max.	*A capacitor prior to measuring the capacitance is heat treated at $150^{\circ}\text{C} + 0/-10^{\circ}\text{C}$ for 1 hour and maintained in ambient air for 24 ± 2 hours.		
Insulation	10,000Mohm or 500Mohm× <i>µ</i> F	Rated Voltage 60~120 sec.		
Resistance	Whichever is smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	250% of the rated voltage		
Voltage	mechanical breakdown			
Temperature X7R				
Characteristics	(From-55℃ to 125℃, Capacitance change should be within ±15%)			
Adhesive Strength	No peeling shall be occur on the	500g·f, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)		
		with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5°C, 3±0.3sec.		
		(preheating : 80~120°C for 10~30sec.)		
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.		
Soldering Heat	Tan δ, IR : initial spec.			
Vibration Test	Capacitance change : within \pm 5% Tan δ , IR : initial spec.	Amplitude: 1.5mm From 10Hz to 55Hz (return: 1min.) 2hours × 3 direction (x, y, z)		
Moisture	Capacitance change: within ±12.5%	With rated voltage		
Resistance	Tan δ: 0.05 max	40±2°C, 90~95%RH, 500+12/-0hrs		
	IR: 500Mohm or 25Mohm × μF			
	Whichever is smaller			
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage		
Resistance	Tan δ: 0.05 max	Max. operating temperature		
	IR: 1,000Mohm or 50Mohm × μF Whichever is smaller	1000+48/-0hrs		
Temperature	Capacitance change: within ±7.5%	1 cycle condition		
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C		
		→ Max. operating temperature → 25°C		
		5 cycle test		

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.